

**2.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER  
POWERDI®123**
**Features**

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- **Qualified to AEC-Q101 Standards for High Reliability**
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Green Molding Compound (No Br, Sb)**
  - **Halogen and Antimony Free. "Green" Device (Note 3)**

**Mechanical Data**

- Case: PowerDI®123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202 Method 208 **(E3)**
- Weight: 0.01 grams (approximate)

PowerDI®123



Top View

**Ordering Information** (Note 4)

Part Number	Case	Packaging
DFLS260-7	PowerDI®123	3000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**


F17A = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: V = 2008)  
 M = Month (ex: 9 = September)

## Date Code Key

Year	2008	2009	2010	2011	2012	2013	2014	2015
Code	V	W	X	Y	Z	A	B	C

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	60	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	42	V
Average Forward Current	I <sub>F(AV)</sub>	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	50	A

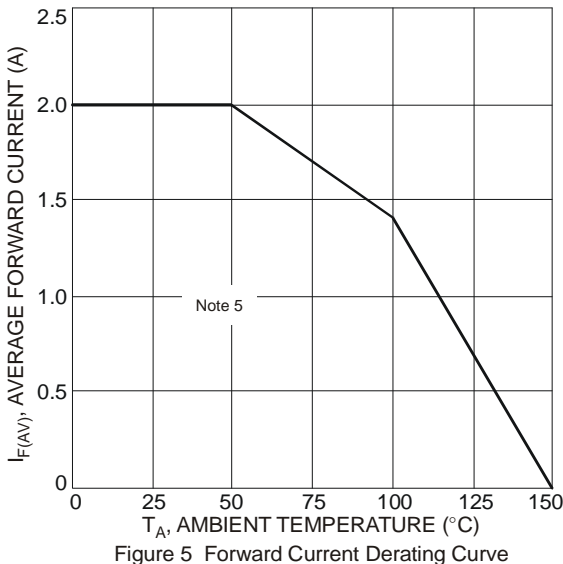
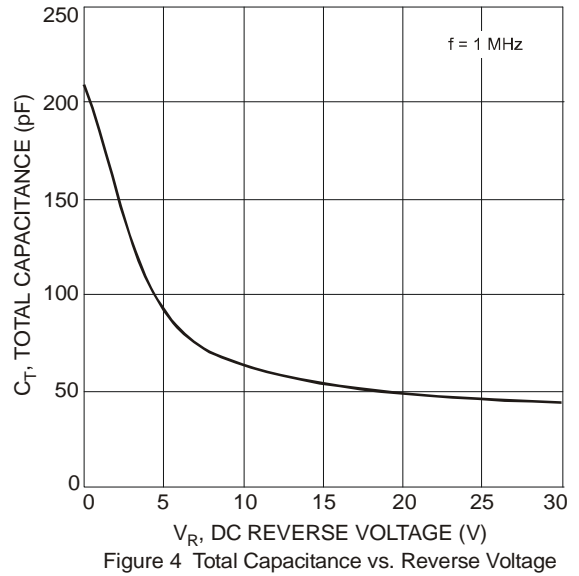
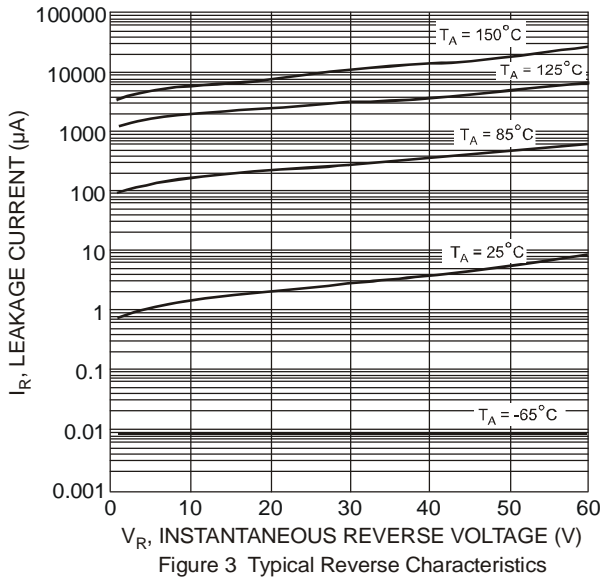
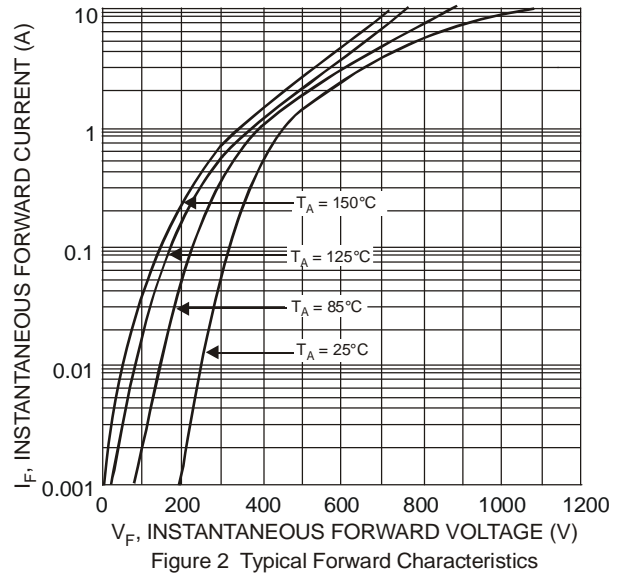
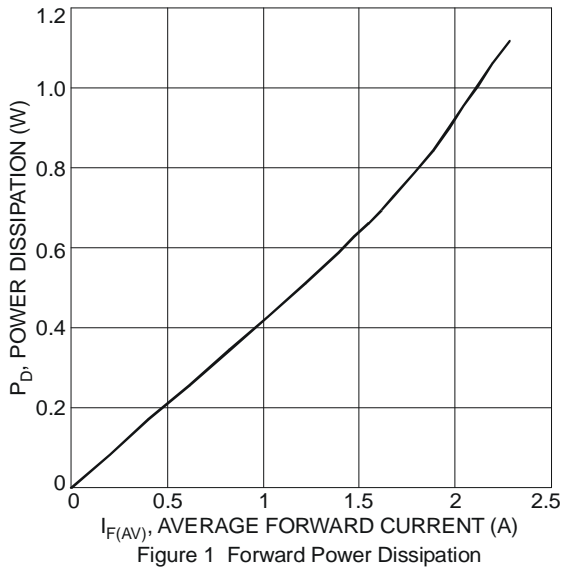
**Thermal Characteristics**

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering Point (Note 6)	R <sub>θJS</sub>	—	6	°C/W
Thermal Resistance Junction to Ambient (Note 5)	R <sub>θJA</sub>	125	—	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150		°C

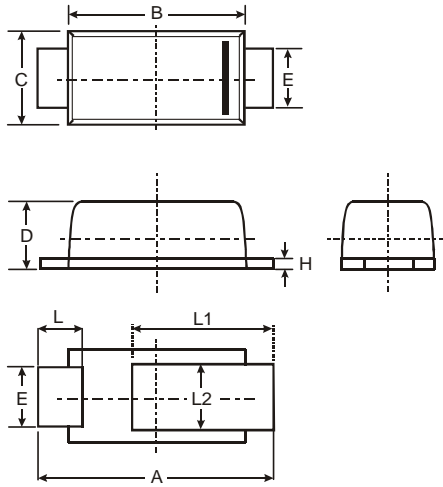
**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V <sub>(BR)R</sub>	60	—	—	V	I <sub>R</sub> = 0.2mA
Forward Voltage	V <sub>F</sub>	—	—	0.62 0.56	V	I <sub>F</sub> = 2.0A, T <sub>A</sub> = +25°C I <sub>F</sub> = 2.0A, T <sub>A</sub> = +125°C
Leakage Current (Note 7)	I <sub>R</sub>	—	—	0.1	mA	V <sub>R</sub> = 60V, T <sub>A</sub> = +25°C
Total Capacitance	C <sub>T</sub>	—	67	—	pF	V <sub>R</sub> = 10V, f = 1.0MHz

- Notes:
5. Part mounted on FR-4 board with 2 oz., minimum recommended copper pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  6. Theoretical R<sub>θJS</sub> calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
  7. Short duration pulse test to minimize self-heating effect.

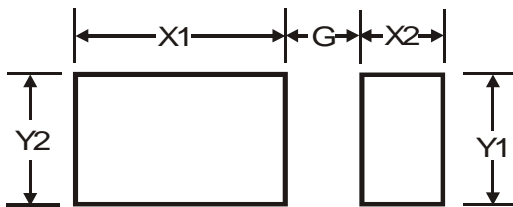


**Package Outline Dimensions**



PowerDI <sup>®</sup> 123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.55	0.75	0.65
L1	1.80	2.20	2.00
L2	0.95	1.25	1.10
All Dimensions in mm			

**Suggested Pad Layout**



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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